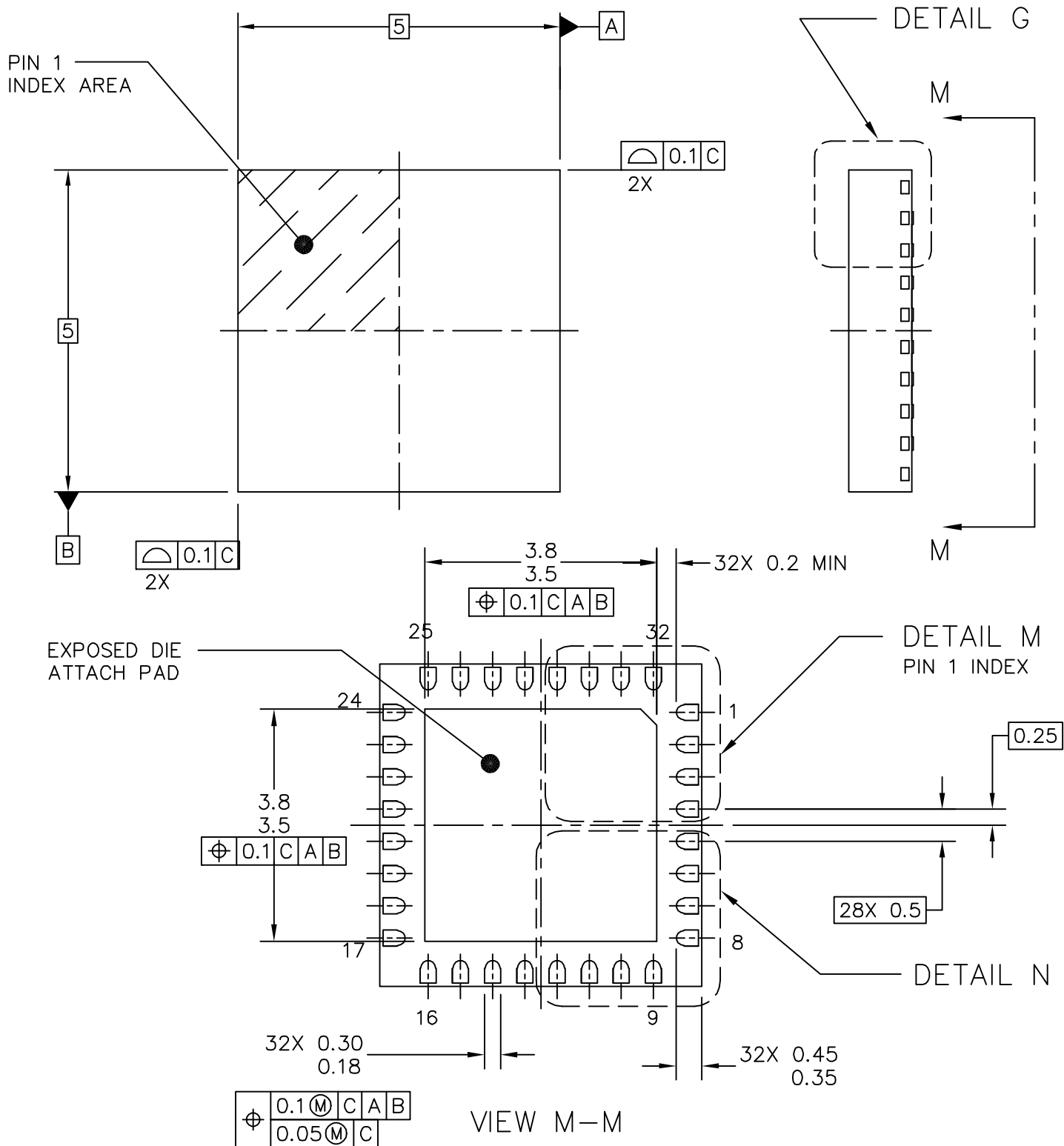
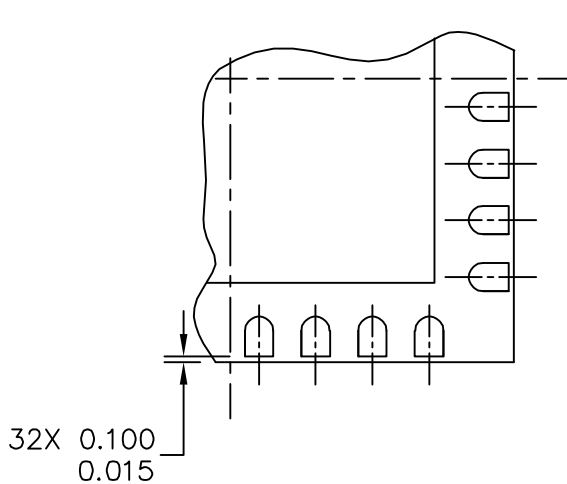
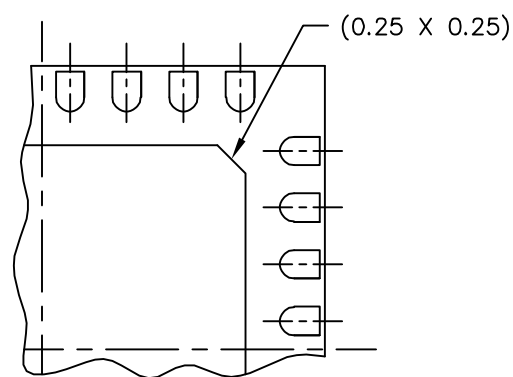




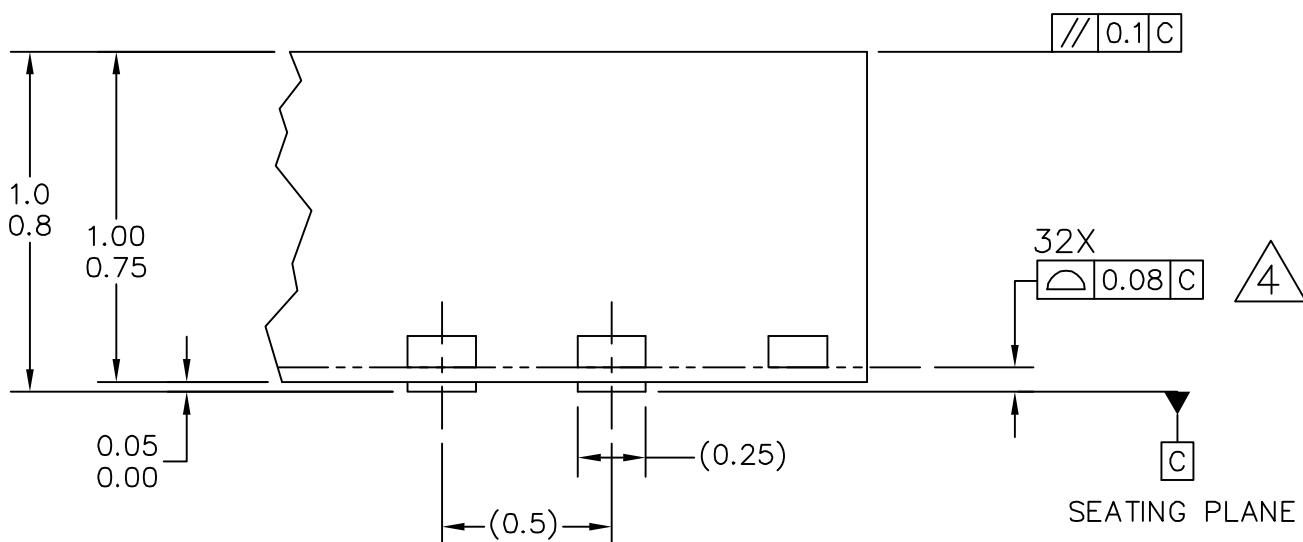
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) 3.6 X 3.6 EP, CASE OUTLINE	DOCUMENT NO: 98ARE10566D		REV: C
	CASE NUMBER: 1582-02		26 FEB 2007
	STANDARD: JEDEC MO-220 VHHD-4		



DETAIL N
PREFERRED CORNER CONFIGURATION



DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL G
VIEW ROTATED 90° CW

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			CASE NUMBER: 1582-02		26 FEB 2007
			STANDARD: JEDEC MO-220 VHHD-4		

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
- △ 4. COPLANARITY APPLIES TO LEADS, AND DIE ATTACH PAD.
5. MINIMUM METAL GAP SHOULD BE 0.2 MM.

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